

产品规格书 DATA SHEET

Part No: MHT151RGBCT REV.4

本产品符合 ROHS 指令有关限制有害物质的环保要求.

日期 DATE	拟制 PREPARED	审核 VERIFIED	批准 APPROVED	
2019-12-03	Bob		Sunny	
	客户签回 CUSTOMER'S APPROVAL			

电 话 Tel: 0518-83286000 传 真 Fax: 0518-83696699

邮件 E-mail: <u>sales@lygmh.com.cn</u> 网址Web: http://www.lygmh.com.cn

地址 ADD: 中国 • 江苏省连云港市灌南经济开发区北环路

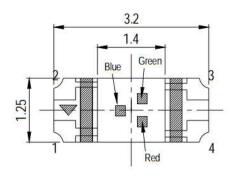
North Around Road, Guannan EDA, Lianyungang City, Jiangsu Province China.

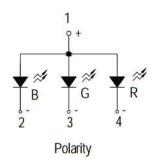


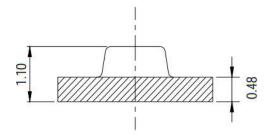
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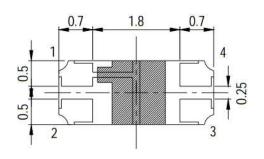
LED SMD

产品外观尺寸 PACKAGE DIMENSIONS

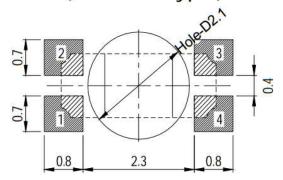








Recommended Solder Pad (Reverse Type)



注意 NOTES:

1. 所有尺寸均为 mm(英寸)

All dimensions are in millimeters. (inches)

2. 如无特殊说明,公差为 0.10mm(0.004")

Tolerance is ±0.10mm(0.004") unless otherwise specified.

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产品特性 FEATURES

- 高可靠性和高稳定性 High intensity and reliability
- 高品质、和低功耗、低成本 High quality, Low power requirement and low cost
- 室外显示屏Outdoor display screen
- 全彩型 Full-color type
- IC 易兼容、易装配 IC compatible, Easy assembly
- 符合 RoHS 指令要求 ROHS COMPLIANC
- 无铅产品 Pb FREE PRODUCTS
- 静电承受能力 2000V/1000V/1000V(HBM) ESD 2000V/1000V /1000V(HBM).

产品特征 Description

- 1206 规格封装 1206package
- 反贴顶部发光

Reverse Type Top View LED

- 胶体颜色:透明
 - Lens Color: Water Clear
- 发光颜色 Emitted color:
 - 红色: Red
 绿色: Green
 - 3. 蓝色: Blue
- 晶片材质 Chips materials:
 - 1. AlGaInP
 - 2. InGaNa
 - 3. InGaNa



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极限参数 Absolute Maximum Ratings(Ta=25℃)

参数	····· 9 -(······ 符号		单位	
Parameter	Symbol	Rating	Unit	
		R:95		
Power Dissipation	PAD	G:95	mW	
Tower Dissipation		B:95		
最大峰值电流	_	R:60		
Peak Forward Current Per Segment	IFP	G:60	mΑ	
(1/10 duty cycle, 0.1ms pulse width)		B:60		
工户使用电流		R:25		
正向使用电流	IF	G:25	mA	
Continuous Forward Current	-	B:25		
		R:5		
	VR	G:5	V	
Reverse Voltage		B:5	•	
工作温度	TOPR	-40℃ to +85℃		
Operating Temperature Range	1011\(\text{10 \cdot 0.}		,	
储藏温度	TSTG	-40℃ to +100℃		
Storage Temperature Range	1313			
回流焊温度	TSOL	260℃		
Soldering Temperature	IOUL	200 €		
I				

Note:

产品对静电敏感,搬运产品时必须小心

The products are sensitive to static electricity and must be carefully taken when handling products.



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光电特性 Optical-Electrical Characteristic(Ta=25℃)

符号	参数	测试条件	最小	标准	最大	单位
Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
	工力工物	R:IF = 20mA	1.7	-	2.4	
VF	正向压降 Forward Voltage	G:IF =20mA	2.8	-	3.6	V
	Torward Voltage	B:IF = 20mA	2.8	-	3.6	
	后点泥虫沟	R:VR = 5V	-	-	10	
IR	反向漏电流 Poverse Current	G: VR = 5V	-	-	10	uA
	Reverse Current –	B: VR = 5V	-	-	10	•
λр	峰值波长 Peak Wavelength	R:IF = 20mA	-	632	-	
		G:IF = 20mA	-	518	-	nm
		B:IF = 20mA	-	468	-	
	主波长 - Dominant Wavelength -	R:IF = 20mA	-	624	-	
λd		G:IF = 20mA	515	-	530	nm
		B:IF = 20mA	460	-	470	
	发光角度	R:IF = 20mA	=	130	=	
$2\theta 1/2$	及几用及 Viewing Angle	G:IF = 20mA	=	130	=	deg
	Viewing Angle	B:IF = 20mA	-	130	-	
	发光强度	R:IF = 20mA	460	618.5	777	
lv		G:IF = 20mA	850	1325	1800	mcd
	Luminous Intensity -	B:IF =20mA	150	289	428	

Notes:

- 1. 发光强度公差为±10%。 Tolerance of Luminous Intensity :±10%.
- 2. 波长公差为±1nm。Tolerance of Dominant Wavelength:±1nm.
- 3. 正向压降公差为±0.1V。Tolerance of Forward Voltage : ±0.1V.



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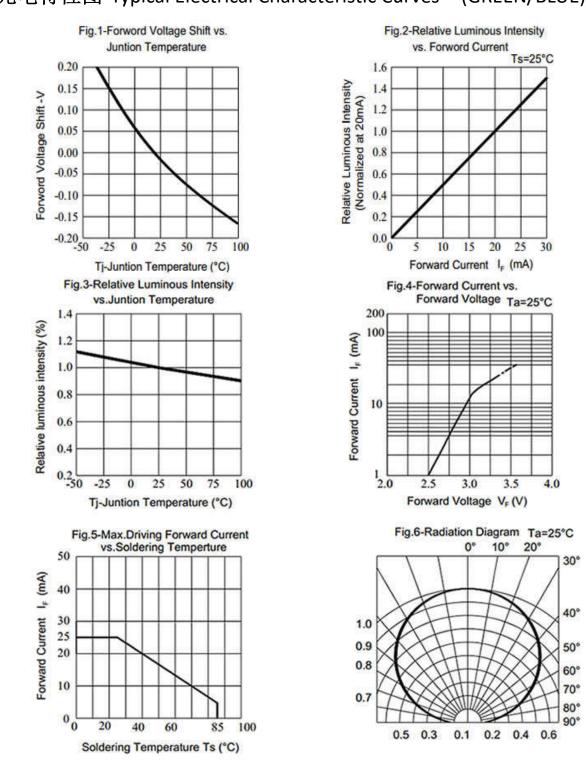
光电特性图 Typical Electrical Characteristic Curves (RED) Fig.1-Forword Voltage Shift vs. Fig.2-Relative Luminous Intensity Juntion Temperature vs. Forword Current Ts=25°C 0.20 1.6 Relative Luminous Intensity (Normalized at 20mA) 0.15 Forword Voltage Shift -V 1.2 0.10 0.05 1.0 0.00 -0.05 -0.100.4 -0.15-0.20 L 0.0 -25 0 25 50 75 15 20 25 Forward Current I_F (mA) Tj-Juntion Temperature (°C) Fig.4-Forward Current vs. Fig.3-Relative Luminous Intensity Forward Voltage Ta=25°C vs.Juntion Temperature 200 1.4 Relative luminous intensity (%) Forward Current I, (mA) 1.2 1.0 0.8 0.6 0.4 25 50 75 100 2.0 2.6 Forward Voltage V_F (V) Tj-Juntion Temperature (°C) Fig.6-Radiation Diagram Ta=25°C Fig.5-Max.Driving Forward Current vs.Soldering Temperture 10° 50 30° Forward Current Ip (mA) 30 1.0 25 0.9 50° 20 0.8 60° 10 70° 0.7 80° 0.3 0.1 0.2 0.4 Soldering Temperature Ts (°C)



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光电特性图 Typical Electrical Characteristic Curves (GREEN/BLUE)





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发光强度等级 Bin Range of Luminous Intensity(IV) RED	Luminous Intensity(IV) RED
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2				
等级	最小值	最大值	单位	条件
Bin Code	Min	Max	Unit	Condition
R	112	180	mcd	@20mA
S	180	285	mcd	@20mA

发光强度等级 Bin Range of Luminous Intensity(IV) GREEN

等级	最小值	最大值	单位	条件
Bin Code	Min	Max	Unit	Condition
T2	360	450	mcd	@20mA
U1	450	565	mcd	@20mA
U2	565	715	mcd	@20mA

发光强度等级 Bin Range of Luminous Intensity(IV) BLUE

等级	最小值	最大值	单位	条件
Bin Code	Min	Max	Unit	Condition
R	112	180	mcd	@20mA
S	180	285	mcd	@20mA

Note:

亮度公差范围: ±10%。Tolerance of Luminous Intensity: ±10%.

主波长等级 Bin Range of Dominant Wavelength(λd) GREEN

等级	最小值	最大值	单位	条件
Bin Code	Min	Max	Unit	Condition
A4	515	520	nm	@20mA
A5	520	525	nm	@20mA
A6	525	530	nm	@20mA

主波长等级 Bin Range of Dominant Wavelength(λd) BLUE

等级	最小值	最大值	单位	条件
Bin Code	Min	Max	Unit	Condition
A5	460	465	nm	@20mA
A6	465	470	nm	@20mA

Notes:

波长公差为±1nm。Tolerance of Dominant Wavelength:±1nm



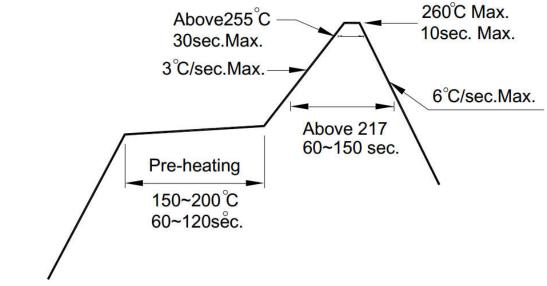
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焊接条件 Soldering Condition

方法 METHOD	焊接条件 SOLDERING CONDITIONS	备注 REMARK
回流焊 Reflow Soldering	260°C for 10 sec.	
烙铁焊 Soldering Iron	350°C for 3 sec.	使用 25W 以下功率的电烙铁 the soldering iron capacity 25W

无铅制程炉温曲线 Pb-free solder temperature profile



Notes:

1. 过回流焊次数不可超过2次。

Reflow soldering should not be done more than two times.

2. 焊接加热过程中不要挤压 LED

When soldering, do not put stress on the LEDs during heating.

3. 焊接完成后,不要用力玩去线路板

After soldering, do not warp the circuit board

4. 客户在设计使用时需串联保护电阻,避免电压波动烧毁发光二极管。

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen)



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LED SMD

可靠度测试及条件 Reliability Test Items and Conditions

编号 No.	项目 Items	测试条件 Test Condition	测试时间 Test Hours/Cycles	样品数量 Sample Size	判定标准 Ac/Re
1	回流焊 Reflow Soldering	260°C/10sec.	6 Min	22pcs	0/1
2	热冲击 Thermal Shock	H : +100°C 5min ∫ 10 sec L : -40°C 5min	300 Cycles	22pcs	0/1
3	温度循环 Temperature Cycle	H:+100°C 15min ∫ 5 min L:-40°C 15min	300 Cycles	22pcs	0/1
4	高温高湿测试 High Temperature/Humidity Reverse Bias	Ta=85℃,85%RH	1000 Hrs.	22pcs	0/1
5	低温贮藏 Low Temperature Storage	Ta= - 40°C	1000 Hrs.	22pcs	0/1
6	高温贮藏 High Temperature Storage	Ta=100℃	1000 Hrs.	22pcs	0/1
7	寿命测试 DC Operation Life	Ta=25˚C IF=20mA	1000 Hrs.	22pcs	0/1

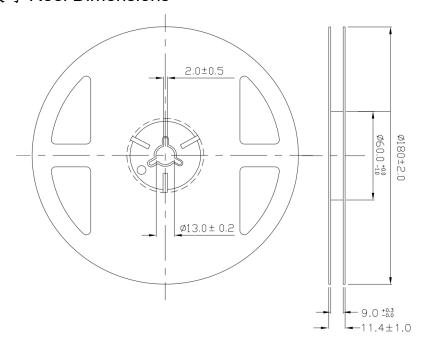


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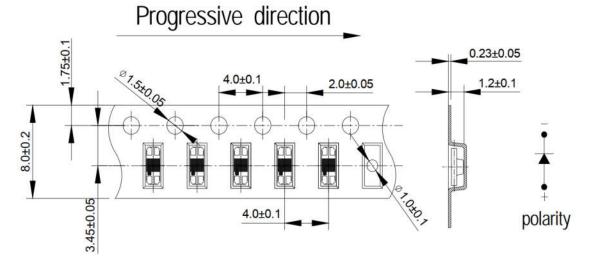
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包装 Packing

1. 卷轴尺寸 Reel Dimensions



2. 载带尺寸 Carrier Tape Dimensions



Notes:

1. 量测公差为±0.1mm,单位是毫米。

Tolerances unless mentioned ±0.1mm,Unit = mm

2. 最小包装数量为每卷 2000 个 (编带反编)

Minimum packing amount is 2000 pcs per reel(Reverse Type)



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储藏 STORAGE

- 1. 发光二极管在出厂后可在温度 30 度以下,湿度 60%以下的环境内保存 1 年。The LED should be stored at 30℃ or less and 60% RH or less after being shipped from MH and the storage life limits are 1 year.
- 2. 在产品准备使用前请不要打开防潮袋。Do not open moisture proof bag before the products are ready to use.
- 3. 打开包装后: 产品暴露在温度 30 度以下湿度 60%以下的 24 小时内用完,若仍然有剩余,请一定要放到防潮柜内储存。After opening the package: The LED's floor life is 24 hr under 30℃ or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 4. 如果吸湿性材料(硅胶)已用完或发光二极管已超过存储时间,应使用以下条件进行烘烤处理,处理: 60±5℃烘烤 5 小时。If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time,baking treatment should be performed using the following conditions.Baking treatment: 60±5℃ for 5 hours.
- 3. 请避免保存在温度变化明显,尤其是高湿度的地方 Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

使用注意事项 Application Restrictions

- 1_生产环境:建议在 20℃~30℃&30%~60%RH 下作业。 Production environment: It is recommended to operate at 20 DEG ~30 DEG &30%~60%RH
- 2. 维修温度建议控制在 280℃以下,持续加热时间不超过 30S。 The service temperature shall be controlled below 280 degrees, and the continuous heating time shall not exceed 30S.
- 3. 维修时避免尖锐物体直接戳到胶体,取料时建议夹取板材两端。 When repairing, the sharp object should be directly punched into the colloid, and when picking the material, it is recommended to clamp both ends of the PCB.

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其他注意事项 Others

footwear, clothes, and floors

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- 5. 发光二极管正向电流方向使用,驱动电路的设计必须使 LED 在关闭的状态下不经受正向或逆向电压,如果反向电压不断应用于发光二极管,它可以导致 LED 损坏。cause migration resulting in LED damage.

The LEDs should be operated with forward bias. The driving circuit must be designed so that the LEDs are not subjected to forward or reverse voltage while it is off. If reverse voltage is continuously applied to the LEDs, it may cause migration resulting in LED damage.